

CLAIMS

1. A DAF tape adhering apparatus comprising,
a wafer secured on a table,
a DAF tape arranged above the wafer,
5 a substantially annular holder for holding
the DAF tape from both sides, and
a gas supplier for supplying gas toward
the DAF tape in the holder,
wherein the gas is discharged toward the
10 DAF tape to swell the DAF tape in the holder toward the
wafer, to thereby adhere the DAF tape to the wafer.
2. A DAF tape adhering apparatus according to
claim 1, wherein the tape is movable toward the DAF tape.
3. A DAF adhering apparatus comprising,
15 an upper kiln,
a lower kiln opposed to the upper kiln,
a DAF tape held by the upper kiln and the
lower kiln, and
a wafer secured on a table in the lower
20 kiln,
wherein a pressure in the upper kiln is
made relatively higher than the pressure in the lower
kiln to swell the DAF tape, to thereby adhere the DAT
tape on the wafer.
- 25 4. A DAF tape adhering apparatus according to
claim 3, wherein the table is movable toward the DAF
tape.
5. A DAF tape adhering apparatus according to
claim 3 or 4, further comprising a gas supplier provided
30 in the upper kiln, wherein gas is supplied by the gas
supplier into the upper kiln to make the pressure in the
upper kiln higher than the pressure in the lower kiln.
6. A DAF tape adhering apparatus according to
claim 3, further comprising a vacuum source connected to
35 the lower kiln, so that the pressure in the lower kiln is
reduced and/or the lower kiln is evacuated to a vacuum.
7. A method for adhering a DAF tape comprising,

securing a wafer on a table,
arranging a DAF tape above the wafer,
holding the DAF tape from both sides by a
substantially annular holder, and

5 supplying gas from a gas supplier toward
the DAF tape to swell the DAF tape toward the wafer, to
thereby adhere the DAF tape on the wafer.

8. A method for adhering a DAF tape according to
claim 7, wherein the table is movable toward the DAF
10 tape.

9. A method for adhering a DAF tape comprising,
securing a wafer on a stage in a lower
kiln,

holding a DAF tape by the lower kiln and
15 an upper kiln opposed to the lower kiln,

making the pressure in the upper kiln
relatively higher than the pressure in the lower kiln to
swell the DAF tape, to thereby adhere the DAF tape on the
wafer.

20 10. A method for adhering a DAF tape according to
claim 9, wherein the table is movable toward the DAF
tape.

11. A method for adhering a DAF tape according to
claim 9 or 10, further comprising supplying gas in the
25 upper kiln by a gas supplier provided in the upper kiln,
to thereby make the pressure in the upper kiln higher
than the pressure in the lower kiln.

12. A method for adhering a DAF tape according to
claim 9, further comprising reducing the pressure in the
30 lower kiln and/or evacuating the lower kiln to a vacuum,
by a vacuum source connected to the lower kiln.